

EAST - [Untitled1-1]

Drafts

Pending

Active

- L11: (12528) substrate near resin
- L12: (1667) 11 and (hole or (through adj hole))
- L13: (3) 12 and (chip or component or capacitor or resistor or inductor) near embedded
- L14: (10) 4965653.URPN.
- L15: (175) 12 and embedded
- L16: (201) (174/265).CCLS.
- L18: (1) 3536565.URPN.
- L28: (218) 12 and ((row and column) or matrix)
- L29: (155) 28 and (IC or chip or component or wafer)
- L30: (413) (324/763).CCLS.
- L31: (4) ("3290756").PN.
- L33: (30) 3290756.URPN.
- L34: (2) ("4979076").PN.
- L35: (13) ("3142783" | "3191098" | "3192307" | "3266125" | "3290756" | "3480836" | "3517272" ..)
- L43: (17) 3142783.URPN.
- L44: (368) (361/764).CCLS.
- L45: (17) ("4299873" | "4417297" | "4800459" | "5045381" | "5153987" | "5324687" | "5401688" ..)
- L46: (201) (174/265).CCLS.

Failed

- (0) H.sub2.O
- (0) 12 near embedded

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DES USPAT EPO (P) DERVENT USOCA

174/265

U	Document ID	Issue Date	Page	Title	Current OR	Current XRe	Retrieval	Inventor	S	C	P	S
1	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6500011	20021231	6	Flexure blank and method of manufacturing the same	439/82	174/262; 174/264;	174/265	Fujita, Norimasa et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
	R1											
2	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6489572	20021203	4	Substrate structure for an integrated circuit package, a	174/259	156/245; 158/298;	174/265	Ho, Mon Nan et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
	R2			Compliant layer for encapsulated columns		174/261;	174/265	Jimarez, Lisa J. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6486415	20021126	8	Through-hole structure and printed circuit board, includi	174/263	174/265;	174/265	Kobayashi, Kaoru et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
	R2			Wave solder application for ball grid array modules with		174/262;						
4	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6486414	20021126	15	Laminate circuit structure and method of fabrication	174/261	174/255;	174/265	Enroth, Wesley M. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
	R2					174/260;	174/265					
5	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6462285	20021008	14	Press-fit pin connection	174/265	174/263;	174/265	Teshima, Yasuhiro et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
	R2			etching method and state		174/261;						
6	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6459047	20021001	8	Interconnection structure of semiconductor element	174/256	174/255;	174/265	Japp, Robert M. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
	R1			System-on-a-chip with multi-layered metallized thru		174/259;						
7	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6444925	20020903	19		174/262	174/255;	174/265	Umemura, Eiichi	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
	R1					174/261;						
8	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6444918	20020903	25		174/250	174/262;	174/265	Ahn, Kie Y. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
	R1					174/265;						
9	<input type="checkbox"/> <input checked="" type="checkbox"/> US 6441479	20020827	15		257/700	174/262;	174/265					
	R1					174/265;						

Ready